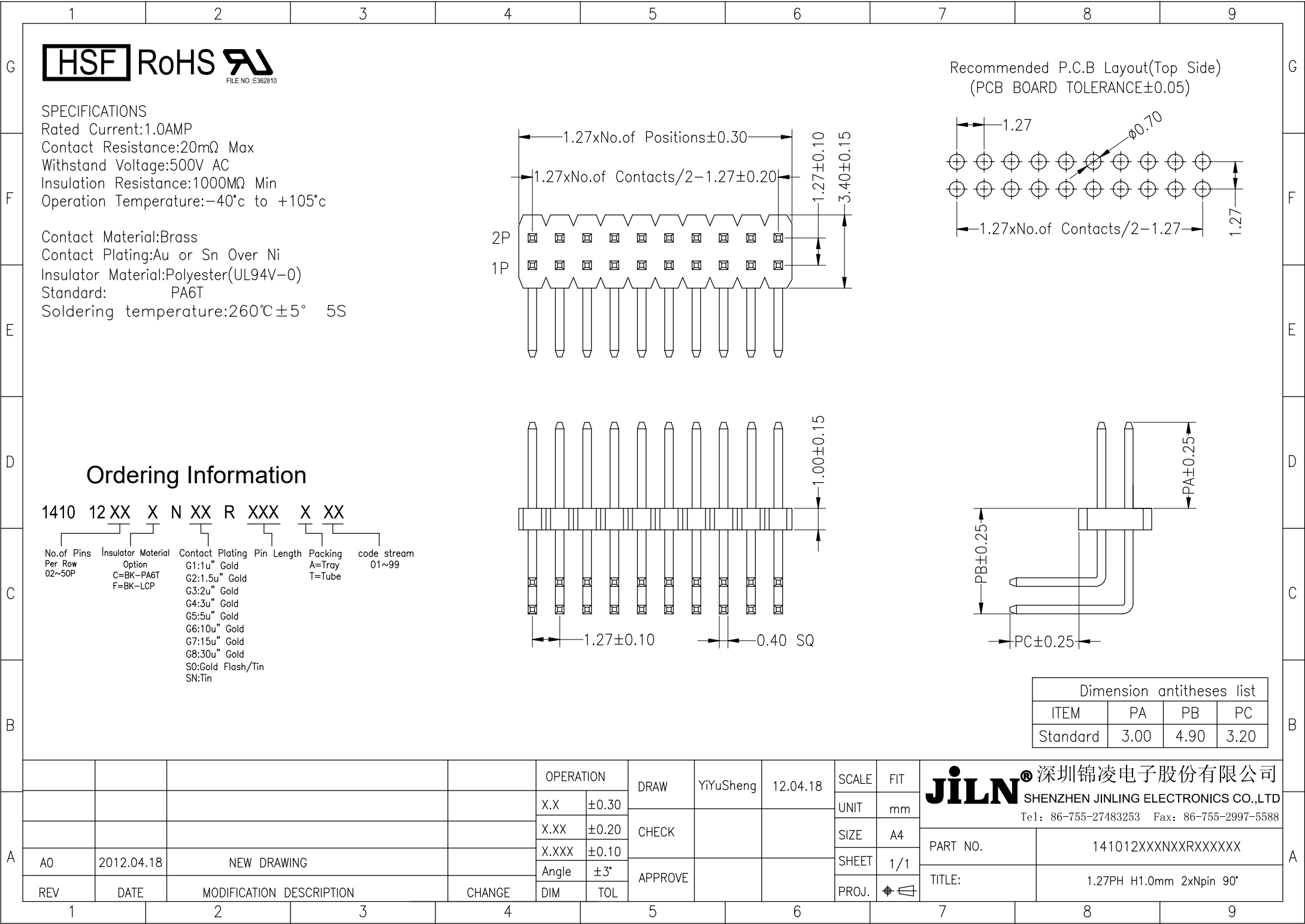




Rated Current:1.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:500V AC
Insulation Resistance:1000MΩ Min
Operation Temperature:-40℃ to +105℃

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V-0)
Standard: PA6T
Soldering temperature: $260^{\circ}\text{C}\pm 5^{\circ}$ 5S

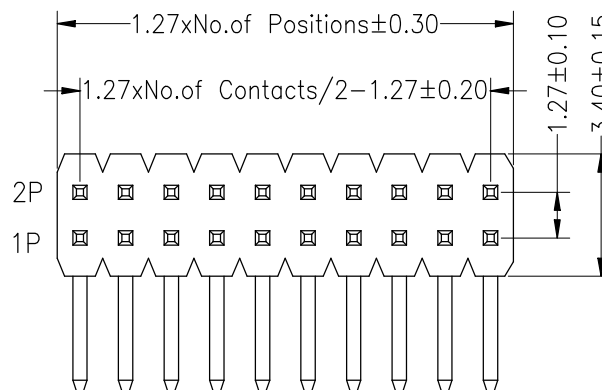


Figure 1: Schematic diagram of the proposed microfluidic chip. The chip is a rectangular device with a grid of circular microfluidic channels. The channels are arranged in a 2x10 grid. The pitch between adjacent channels is 1.27 mm. The channel diameter is 0.70 mm. The total width of the chip is $1.27 \times \text{No. of Contacts} / 2 + 1.27$ mm. The total height of the chip is $1.27 \times \text{No. of Contacts} / 2 + 1.27$ mm.

1410 12 XX X N XX R XXX X XX

No. of Pins Per Row 02~50P

Insulator Option C=BK-PA6T F=BK-LCP

Material

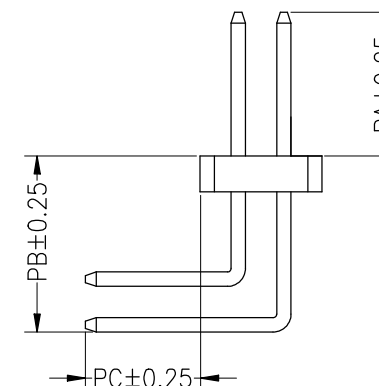
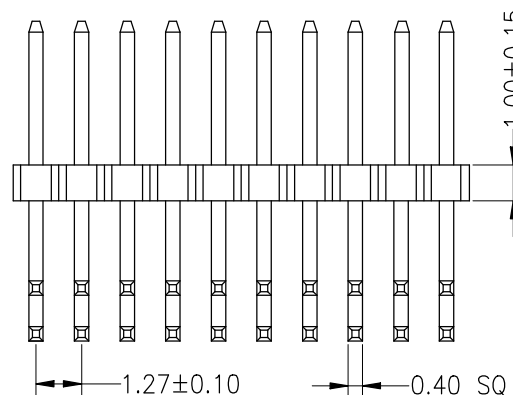
Contact G1:1u" Gold G2:1.5u" Gold G3:2u" Gold G4:3u" Gold G5:5u" Gold G6:10u" Gold G7:15u" Gold G8:30u" Gold S0:Gold Flash/Tin SN:Tin

Plating

Pin Length

Packing A=Tray T=Tube

code stream 01~99



Dimension antitheses list			
ITEM	PA	PB	PC
Standard	3.00	4.90	3.20

				OPERATION		DRAW	YiYuSheng	12.04.18	SCALE	FIT	JILN®深圳锦凌电子股份有限公司 SHENZHEN JINLING ELECTRONICS CO.,LTD Tel: 86-755-27483253 Fax: 86-755-2997-5588	
				X.X	±0.30				CHECK			
				X.XX	±0.20	SIZE	A4					
A0	2012.04.18	NEW DRAWING		X.XXX	±0.10	APPROVE			SHEET	1/1	PART NO.	141012XXXNXXRXXXXXX
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	Angle	±3°				PROJ.		TITLE:	1.27PH H1.0mm 2xNpin 90°
				DIM	TOL							